

04-01-2008



HEET

To the Director of the U.S. Patent and Trademark Office

103493297

Send all correspondence to the address(es) listed below. If you are changing documents or the new address(es) below.

1. Name of conveying party(ies):
Hiroyuki Ishibashi

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: Funai Electric Co., Ltd.

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Osaka 574-0013 JAPAN

City:

State:

Country: Zip:

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): March 6, 2008

Assignment Merger Change of Name

Security Agreement Joint Research Agreement

Government Interest Assignment

Executive Order 9424, Confirmatory License

Other

4. Application or patent number(s):

A. Patent Application No.(s)

This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Robert J. Gaybrick
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6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

Authorized to be charged by credit card

Authorized to be charged to deposit account

Enclosed

None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers Expiration Date

b. Deposit Account Number 50-0310

Authorized User Name: Mary Jane Boswell

9. Signature:

Mary Jane Boswell
Signature

March 25, 2008
Date

Mary Jane Boswell - 33,652
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

2

03/31/2008 11:40AM 00000001 500110 12076909
01:PC:3892 40:00:00

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

**CONNECTOR SUBSTRATE AND SPEAKER
INPUT TERMINAL CONNECTION STRUCTURE**

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Application No. _____); and

WHEREAS, FUNAI ELECTRIC CO., LTD., a corporation of Japan, whose post office address is 7-7-1, Nakagaito, Daito-shi, Osaka 574-0013 Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed March 25, 2008) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of First Assignor	Assignor's Signature	Date
Hiroyuki ISHIBASHI	Hiroyuki ISHIBASHI	Mar. 6. 2008
Address C/O FUNAI ELECTRIC CO., LTD., 7-7-1, Nakagaito, Daito-shi, Osaka 574-0013 Japan		Citizenship Japan